

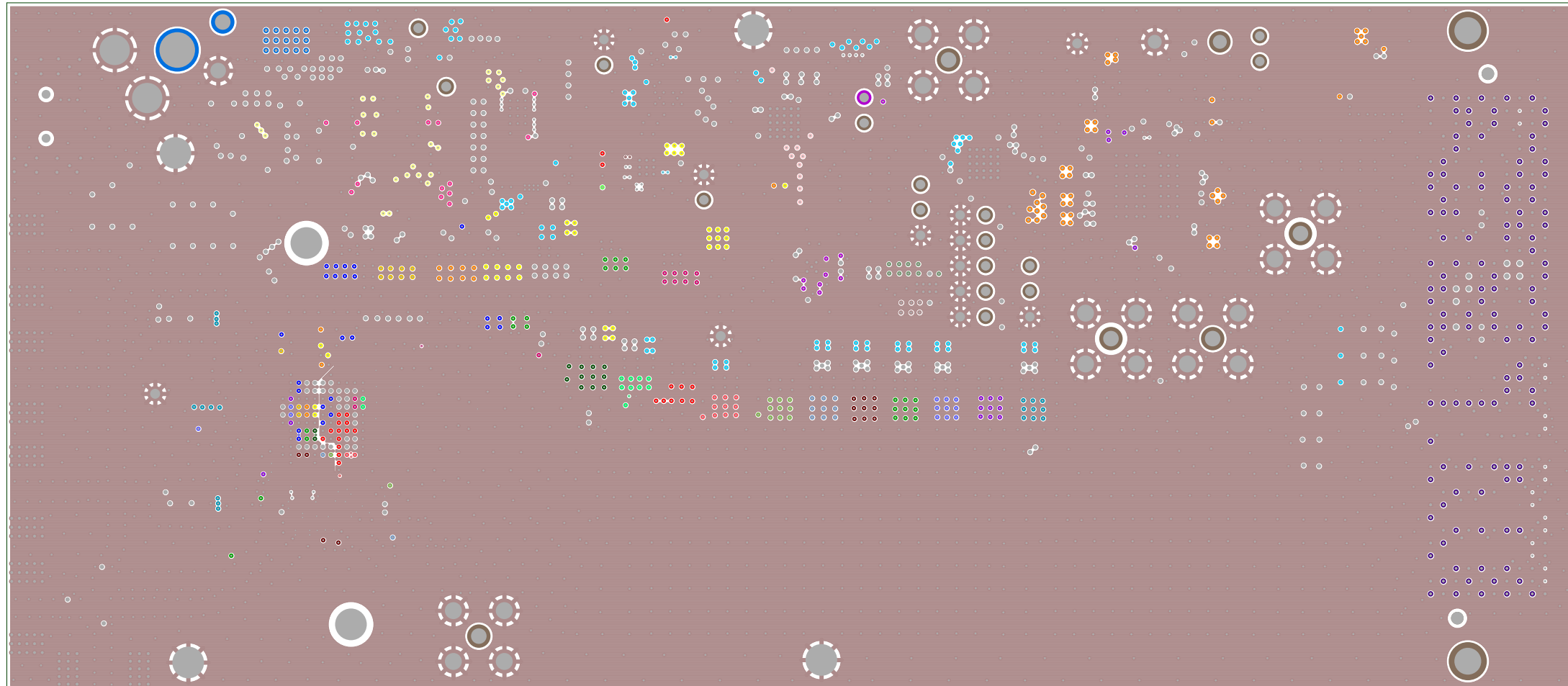
TEXAS INSTRUMENTS INC.

■ DAC38RF83EVM
 ■ DAC38RF80EVM
 PCB REV E

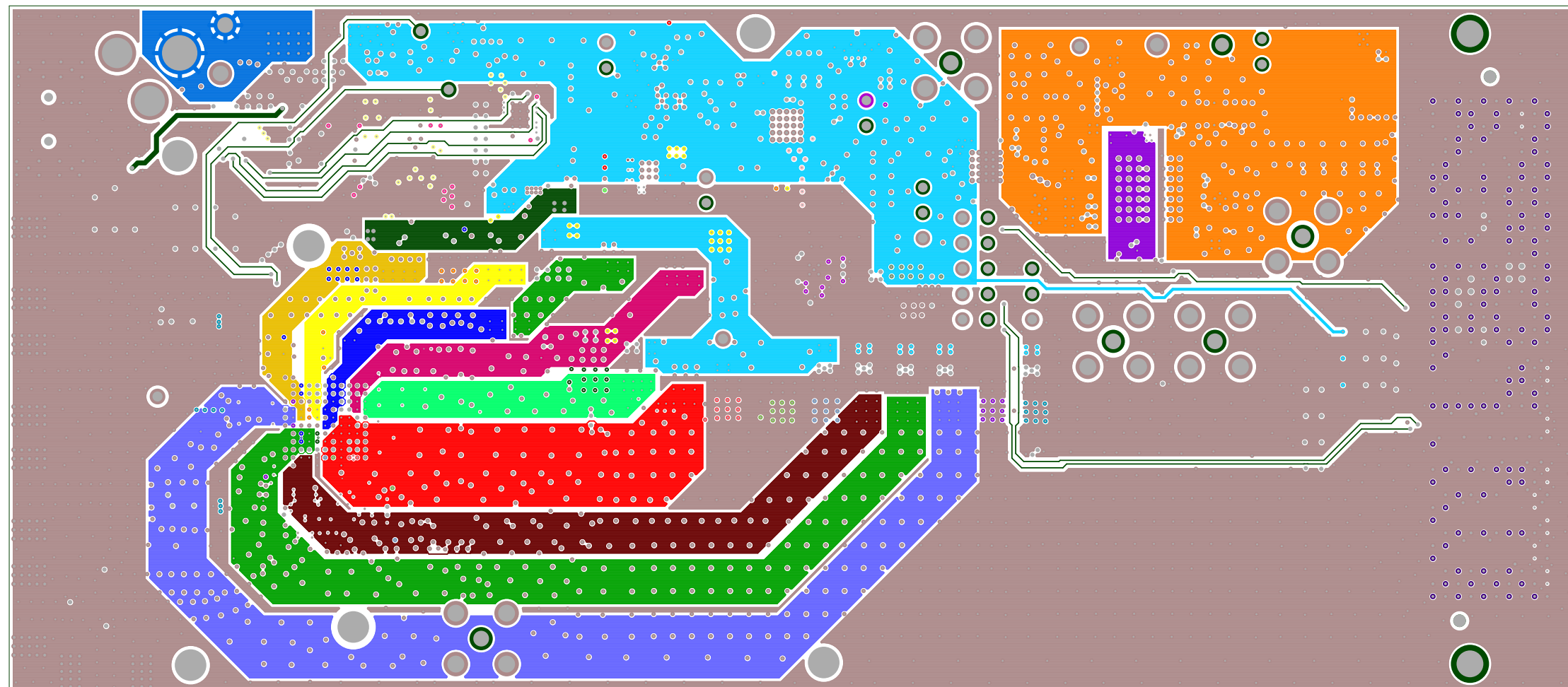
S/N: [REDACTED]

Made in U.S.A.

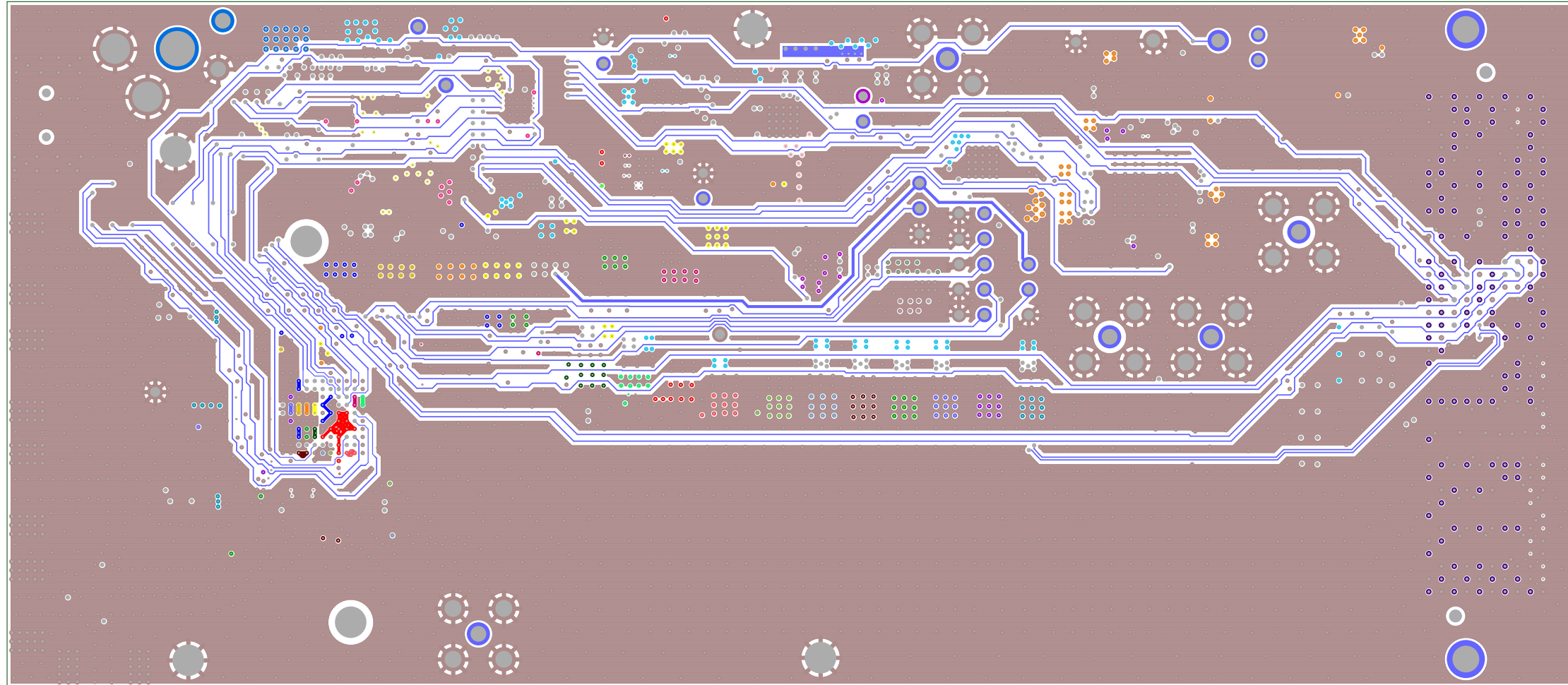
TEXAS INSTRUMENTS, INC.
 DAC38RF8xEVM PCB REV E
 SILEKSCREENSTOP



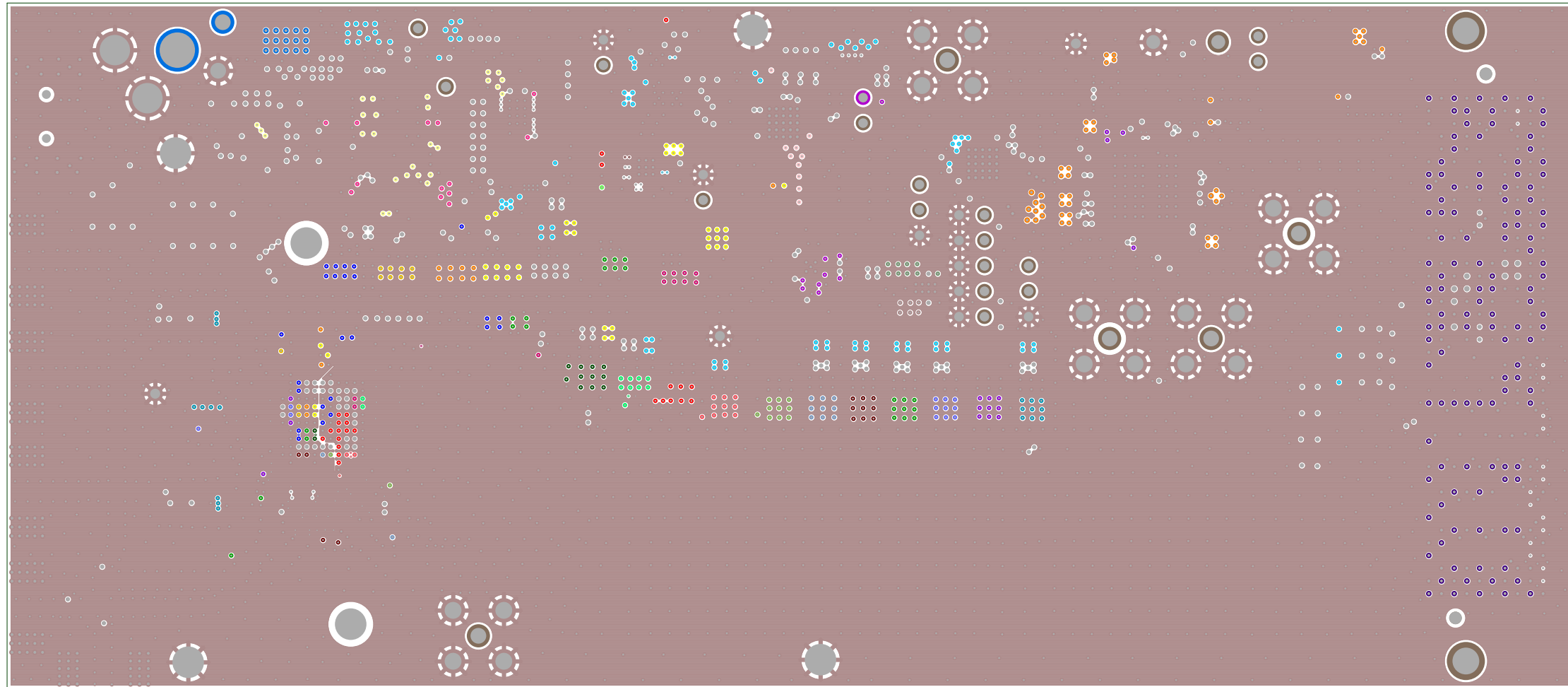
TEXAS INSTRUMENTS, INC.
DAC38RF8x_EVM PCB REV E
LAYER 2 - GND



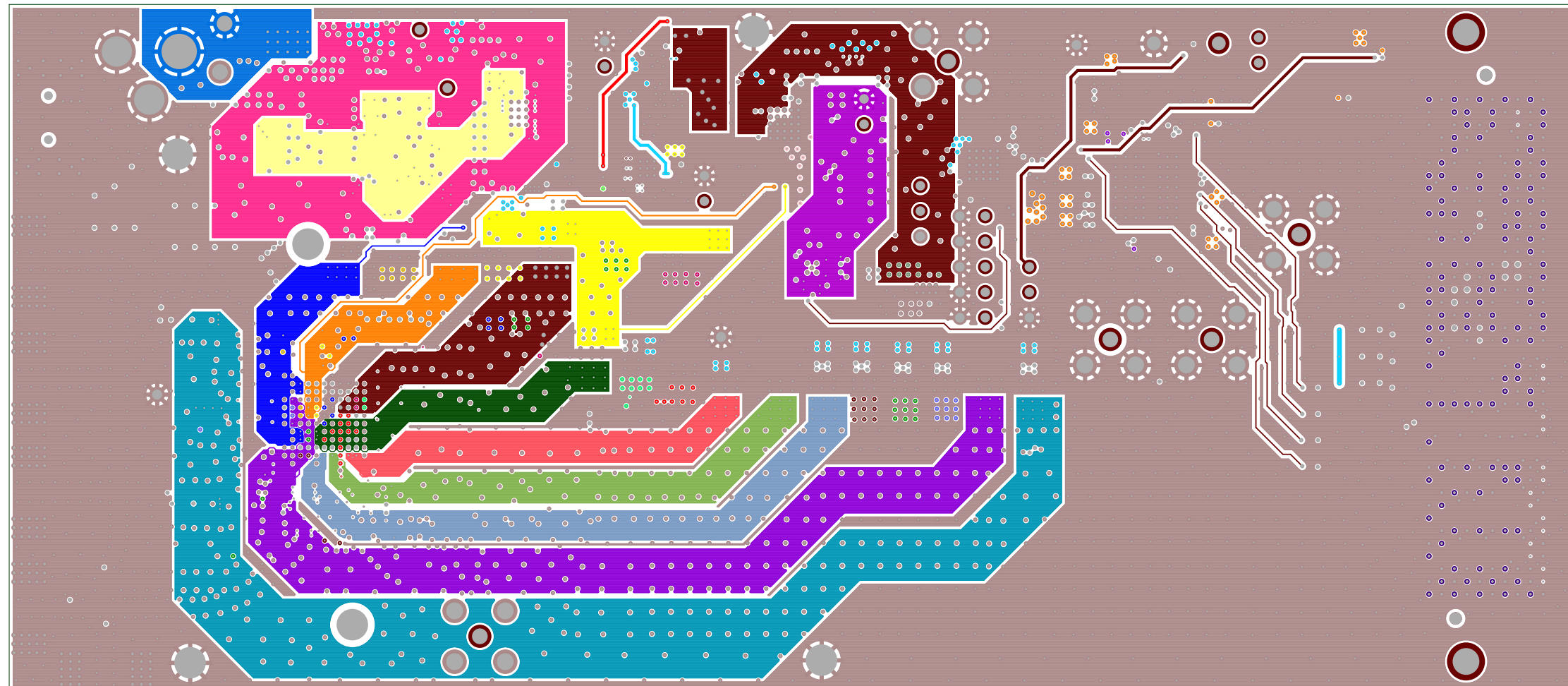
TEXAS INSTRUMENTS, INC.
DAC38RF8xEVM PCB REV E
LAYER 3 - POWER



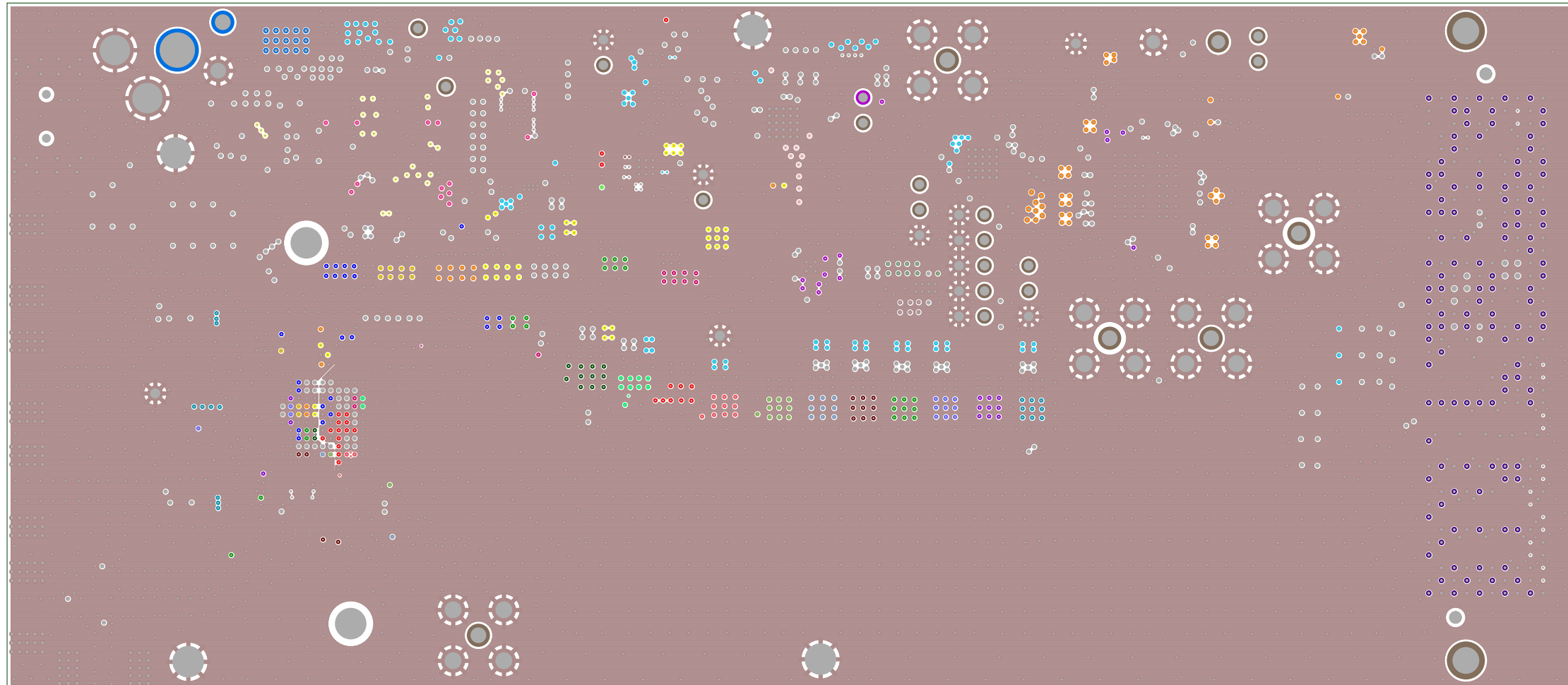
TEXAS INSTRUMENTS, INC.
DAC38RF8xEVM PCB REV E
LAYER 4 - SIGNAL



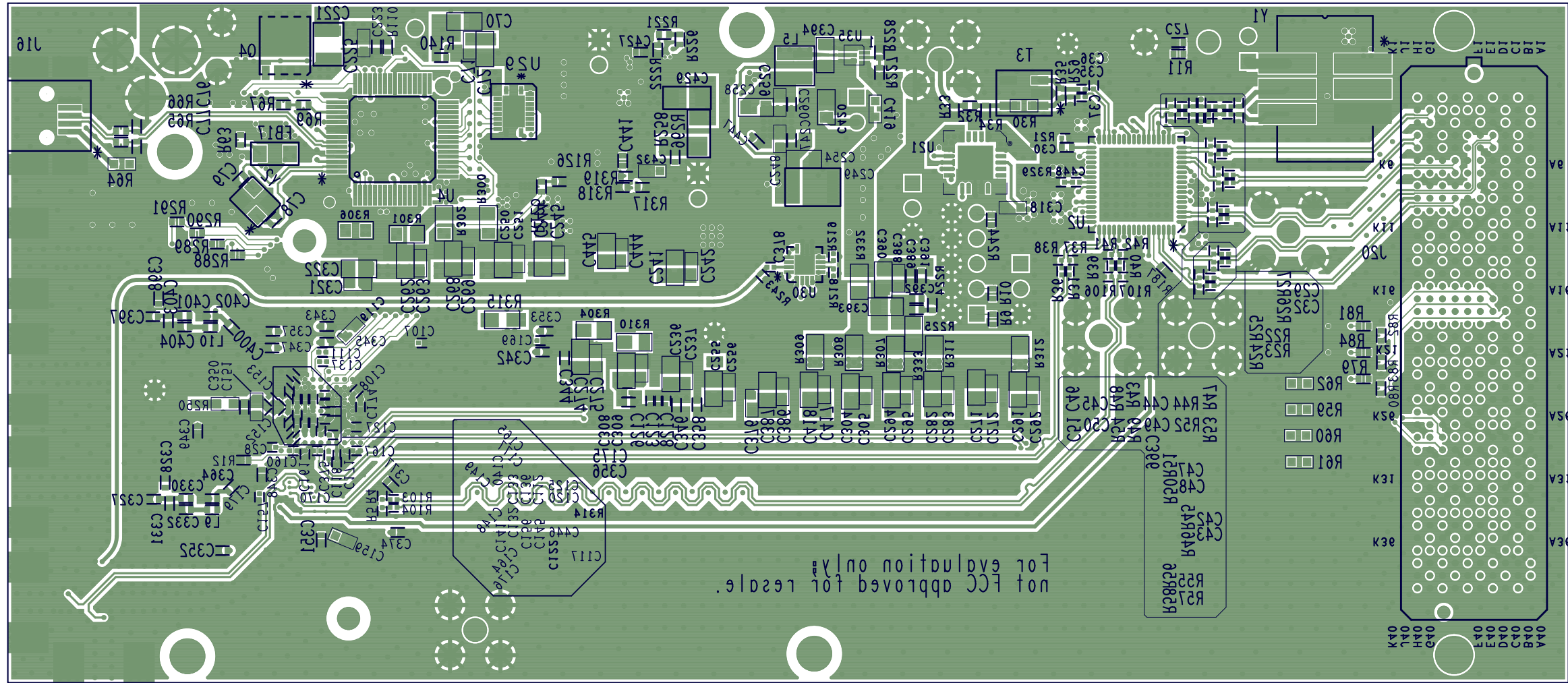
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DAC38RF8xEVM PCB REV E
LAYER 5 - GROUND



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DAC38RF8xEVM PCB REV E
LAYER 6 - POWER/SIGNAL



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DAC38RF8xEVM PCB REV E
LAYER 7 - GROUND

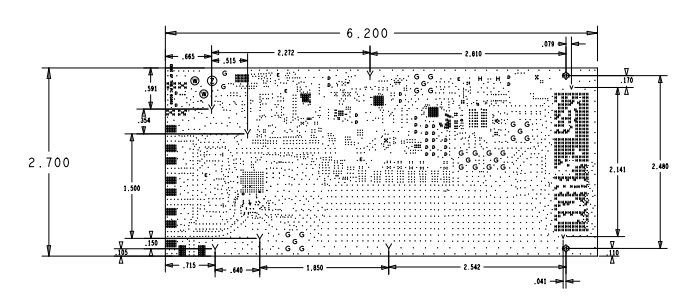
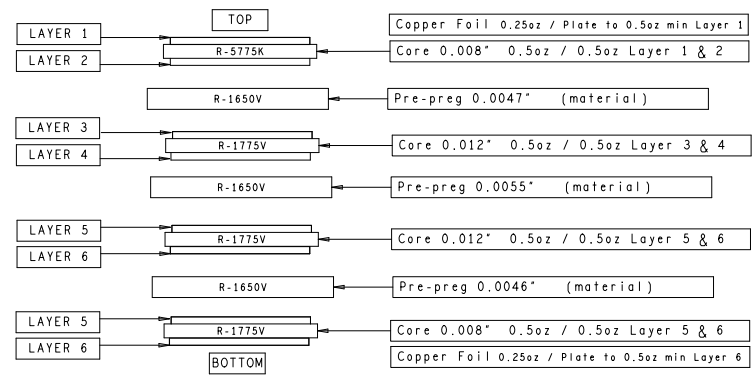


TEXAS INSTRUMENTS, INC.
 DAC38RF8xEVM PCB REV E
 LAYER SCREEN BOTTOM

- UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.
- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS. IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES. IPC-6012 / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, CLASS 2, CURRENT REVISION. IPC-A-600 / ACCEPTABILITY OF PRINTED BOARDS, CLASS 2, CURRENT REVISION.
 - VIA 8 & 10MIL SIZES APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003/- .010$. HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003$.
 - REGISTRATION TOLERANCE: ARTWORK $\pm .002$. ALL HOLE CENTERS $\pm .005$ FROM DIMENSION DATUM.
 - MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH. FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
 - PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0. MATERIAL: MULTI-LAYER (SEE DETAIL "A") SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES. COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062" \pm 10%
 - MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
 - SMOBC/IMMERSION GOLD: 2 - 8 μ IN OVER 118-236 μ IN NICKEL PLATING.
 - SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT) COLOR = RED (0.001 TO 002" THICK OVER METAL).
 - SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE. REGISTRATION TOLERANCE TO BE $\pm .005$. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
 - P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
 - BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
 - BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 19MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED \pm 10%.
- ALL OUTER LAYERS USING A 9MIL TRACE WIDTH AND 6MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL \pm 10%.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 4MIL. MINIMUM COPPER CONDUCTOR SPACING IS: 3.5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY. MAX REFLOW OF 260 DEGREES C (6 PASSES).
- ALL THROUGH VIAS TO BE FILLED WITH NON-CONDUCTIVE MATERIAL. FILLED VIAS TO BE PLATED AFTER PLUGGING TO PRESENT FLAT SURFACE TO DEVICE. NO POTHOLES.

ZONE		LTR		REVISIONS		DATE	APPROVED
				DESCRIPTION			



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	6.0	PLATED	109
.	8.0	PLATED	8
*	8.0	PLATED	14
.	8.0	PLATED	2720
.	10.0	PLATED	108
*	12.0	PLATED	528
*	38.0	PLATED	24
*	40.0	PLATED	5
H	55.0	PLATED	2
o	62.0	PLATED	7
o	67.0	PLATED	20
o	106.0	PLATED	2
o	120.0	PLATED	2
Y	125.0	PLATED	4
o	140.0	PLATED	1
*	35.43	NON-PLATED	2
v	50.0	NON-PLATED	2
Y	125.0	NON-PLATED	2

TEXAS INSTRUMENTS, INC.
DAC38RF8x8VEM PCB REV E

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES \pm .XX \pm .01 \pm .	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING DAC38RF8x8VEM	
DRAWN L. NGUYEN	03-07-16	REV. E		
MATERIAL SEE NOTE 5	ENG E. DWOBENG	03-07-16	DRAWING NO.	
FINISH SEE NOTE 7, 8, 9			SCALE NONE	SHEET 1 OF 1
DO NOT SCALE DRAWING				

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